

Docket No.: JCLA30574

Form 1595 (Rev. 09/04)	RECORDATION FORM COVER SHEET	U.S. Department of Commerce Patent and Trademark Office
<u>PATENTS ONLY</u>		

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

<p>1. Name of conveying party(ies):</p> <table style="width:100%;"> <tr> <td style="width:50%;">Names(s)</td> <td style="width:50%;">Date of Execution</td> </tr> <tr> <td>Chian , Ming-Chung</td> <td>April 8, 2009</td> </tr> <tr> <td>Cheng , Tsan-Yao</td> <td>April 8, 2009</td> </tr> <tr> <td>Lin , Li-Cheng</td> <td>April 8, 2009</td> </tr> <tr> <td>Tsai , Hong-Hsiang</td> <td>April 8, 2009</td> </tr> </table>	Names(s)	Date of Execution	Chian , Ming-Chung	April 8, 2009	Cheng , Tsan-Yao	April 8, 2009	Lin , Li-Cheng	April 8, 2009	Tsai , Hong-Hsiang	April 8, 2009	<p>2. Name/address of receiving Party(ies):</p> <p>Winbond Electronics Corp.</p> <p>No. 8, Keya Rd. I , Daya Township, Central Taiwan Science Park, Taichung County, 428, Taiwan, R.O.C.</p>
Names(s)	Date of Execution										
Chian , Ming-Chung	April 8, 2009										
Cheng , Tsan-Yao	April 8, 2009										
Lin , Li-Cheng	April 8, 2009										
Tsai , Hong-Hsiang	April 8, 2009										
<p>3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Other <input type="checkbox"/> Change of Name <input type="checkbox"/> Reassignment</p>	<p>Add'l name(s)/address(es) of receiving parties Attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>										


4. Application number(s) or patent number(s):	
<p>A. Patent Application No. (s)</p> <p style="text-align: center;">12/436,266</p> <p style="text-align: right;">Additional numbers attached?</p>	<p>B. Patent No. (s)</p> <p style="text-align: center;"><input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>

<p>5. Name and address of party to whom Correspondence concerning document should be mailed:</p> <p style="text-align: center;">J. C. Patents 4, Venture Suite 250 Irvine, CA. 92618 Tel: (949) 660-0761 Fax: (949) 660-0809 E-mail: jcpi@email.msn.com</p>	<p>6. Total No. of applications and patents involved:</p> <p style="text-align: center;">ONE(1)</p> <p>7. Total fee (37 CFR §3.41): <u>\$40.00</u> <input type="checkbox"/> Authorized to be charge by credit card <input checked="" type="checkbox"/> Authorized to be charge to deposit account <input type="checkbox"/> Enclosed <input type="checkbox"/> None required (government interest not affecting title)</p> <p>8. Payment Information a. Credit Card Last Numbers _____ Expiration Date _____ b. Deposit Account Number <u>50-0710</u> Authorized User Name <u>Jiawei Huang</u></p>
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Atty Docket No.: JCLA30574

9. Statement and Signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

<p><u>Jiawei Huang</u> Name of Person Signing Registration No. 43,330</p>	 Signature	<p><u>5-6-2009</u> Date</p>	<p>Total number of pages including cover sheet, attachments, and documents: 3</p>
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ASSIGNMENT

WHEREAS,

- | | |
|---------------------|---------------------|
| 1. Ming-Chung Chian | 2. Tsan-Yao Cheng |
| 3. Li-Cheng Lin | 4. Hong-Hsiang Tsai |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SEMICONDUCTOR STRUCTURE AND METHOD OF FABRICATING THE SAME**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Winbond Electronics Corp.
of No. 8, Keya Rd. I, Daya Township, Central Taiwan Science Park, Taichung
County, 428, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Ming - Chung Chian Date: 2009.04.08
Sole or First Joint Inventor: Ming-Chung Chian

Signature: Tsan - Yao Cheng Date: 2009.04.08
Second Joint Inventor (if any): Tsan-Yao Cheng

Signature: Li - Cheng Lin Date: 2009-04-08
Third Joint Inventor (if any): Li-Cheng Lin

Signature: Hong Hsiang Tsai Date: 2009-04-08
Fourth Joint Inventor (if any): Hong-Hsiang Tsai